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## BGA Planting Kit for Siemens series x65, x7x

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Product ID: 1784

Price: **14.00 EUR**

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Product weight: **0.02 kg**

### Description:

BGA Planting Kit for Siemens series x65, x7x it's professional stainless Planting Kit for making IC Tin ball is needed tool when you have to exchange BGA parts of your phone. List of supported phones: A70, A75, AX75, C75, CX75, M75, Siemens CX70, Siemens X65 - np. A65, C65, CV65, CT65, CF65, CX6C, CX65, CXV65, S65, SV65, SL65, M65, MV65 and similar...

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